**Product data sheet** 

## 1. General description

Hyperfast power diode in a SOD142 (2-lead TO247) plastic package.

#### 2. Features and benefits

- Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- · Low leakage current
- · Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT

## 3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_R$	reverse voltage	DC	-	-	600	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; T <sub>mb</sub> ≤ 41 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	-	-	60	Α
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 µs; T <sub>mb</sub> ≤ 41 °C; square-wave pulse	-	-	120	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	-	-	600	Α
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	-	-	660	Α
Static chara	acteristics					
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	2	2.6	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.55	2	V
Dynamic ch	naracteristics					
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}$ ; $V_R = 30 \text{ V}$ ; $dI_F/dt = 50 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7	-	-	50	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu$ s; $T_j = 25 ^{\circ}\text{C}; Fig. 7$	-	40	-	ns

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**BYC60W-600P** 

### Hyperfast power diode

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu s; T_i = 125 \text{ °C}; Fig. 7$	-	101	-	ns

## 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		K — A 001aaa020
2	Α	anode		001aaa020
mb	mb	mounting base; connected to cathode	TO-247 (SOD142)	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package					
	Name	Description	Version			
BYC60W-600P	TO-247	Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247	SOD142			

## 7. Limiting values

#### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	DC	-	600	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; T <sub>mb</sub> ≤ 41 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	-	60	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 µs; T <sub>mb</sub> ≤ 41 °C; squarewave pulse	-	120	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	-	600	А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	-	660	А
T <sub>stg</sub>	storage temperature		-55	175	°C
T <sub>j</sub>	junction temperature		-	175	°C

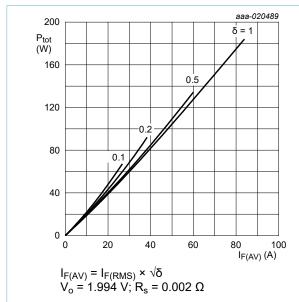


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

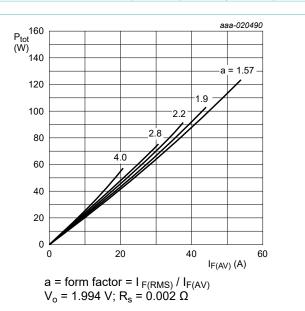


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

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BYC60W-600P

#### Hyperfast power diode

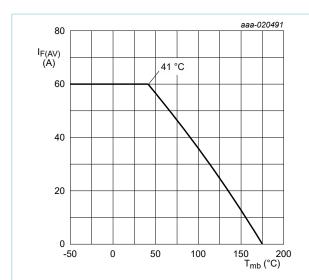


Fig. 3. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

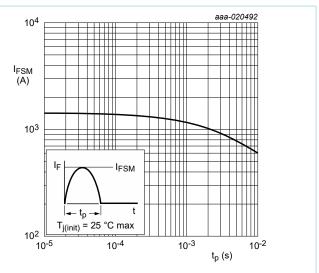


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

#### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	with heatsink compound; Fig. 5	-	-	1	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

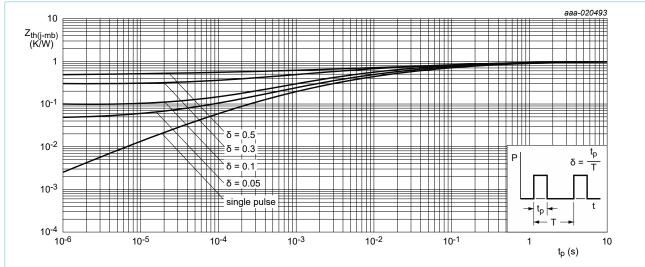


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values

#### 9. Characteristics

**Table 6. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics		,			_
$V_{F}$	forward voltage	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	2	2.6	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.55	2	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	2	10	μΑ
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 125 °C	-	-	500	μΑ
Dynamic ch	naracteristics					
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	50	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu$ s; $T_j = 25 \text{ °C}; Fig. 7$	-	40	-	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu$ s; $T_j = 125 ^{\circ}\text{C}; Fig. 7$	-	101	-	ns
I <sub>RM</sub>	peak reverse recovery current	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A/}$ $\mu$ s; $T_j = 25 ^{\circ}\text{C}; Fig. 7$	-	3.7	-	А
		$I_F = 60 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu$ s; $T_j = 125 ^{\circ}\text{C}; Fig. 7$	-	11	-	А
Q <sub>r</sub>	-	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/$ $\mu$ s; $T_j = 25 ^{\circ}\text{C}; Fig. 7$	-	74	-	nC
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A/}$ $\mu$ s; $T_i = 125 ^{\circ}\text{C}; Fig. 7$	-	559	-	nC

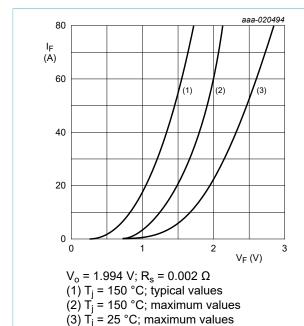


Fig. 6. Forward current as a function of forward voltage

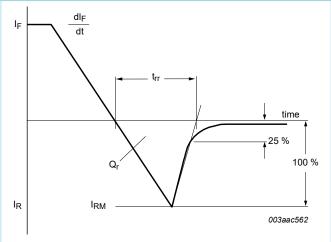
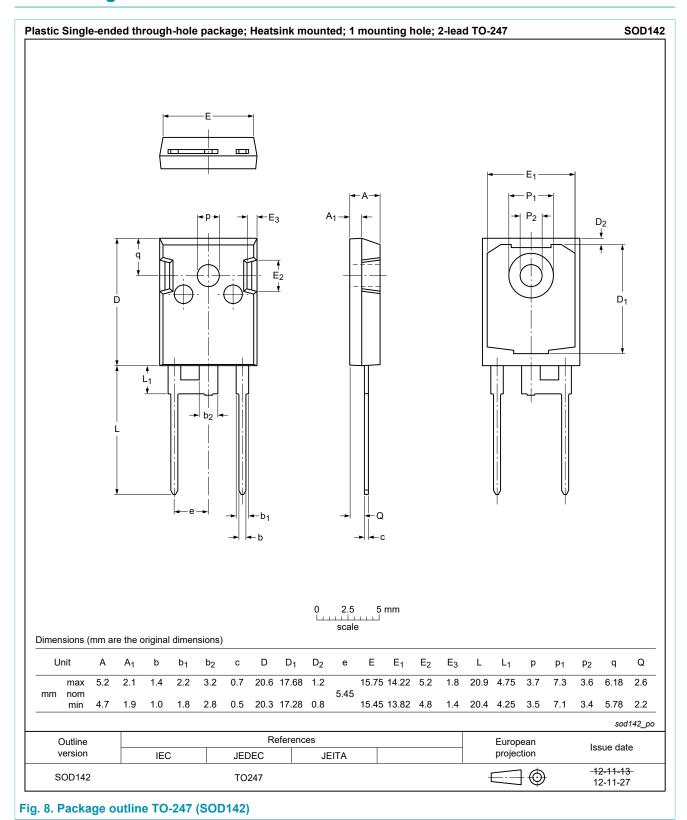


Fig. 7. Reverse recovery definitions; ramp recovery

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## 10. Package outline



### 11. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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